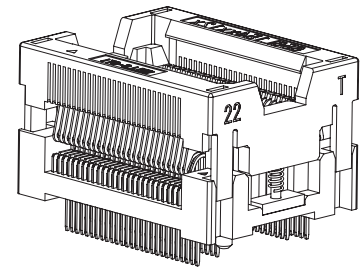
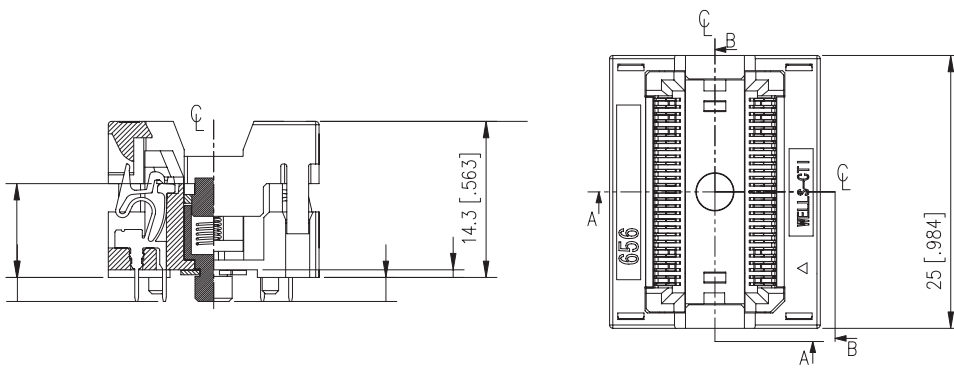
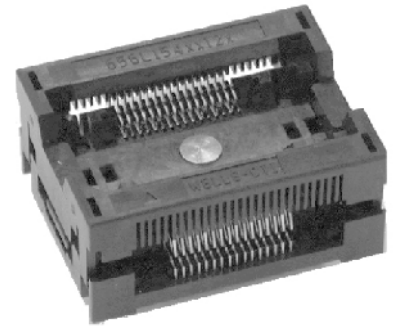


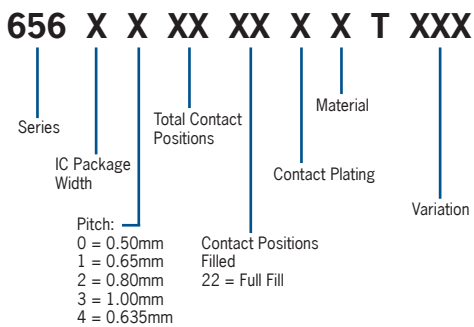


656T SERIES THERMALLY ENHANCED XSOP

- Open top, zero insertion force design for automatic loading
- Thermal contact for interfacing to thermal pad on package
- Thermal contact is timed to interface last and retract first during socket actuation
- Proven, highly reliable, pre-loaded I/O contacts
- Dual pinch I/O contacts
- Thru hole design



DESCRIPTION & ORDERING INFORMATION



MATERIALS & SPECIFICATIONS

- Socket Body: PEI or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Normal Force: 35~45 grams
- Contact Resistance: 50 mΩ max
- Dielectric: 300V AC for 1 minute
- Temperature Rating: 150°C
- Insulation Resistance: 5,000 MΩ @ 500V DC
- Durability: 10,000 cycles min.
- Thermal Pin Power Dissipation: 2W minute

Lead Count	Pitch e (mm)	Package Dimensions (mm)			Part Number	Socket Dimensions (mm)	
		Width (E1)	Lead Tip to Tip (E)	Length (D)		Length (A)	Width (B)
32	0.65	7.50	10.30	11.10 max	656L1543212T	25.00	19.30
36	0.65	7.50	10.30	12.79 max	656L1543612T	25.00	19.30
52	0.65	7.50	10.30	18.10 max.	656L1545212T	25.00	19.30
54	0.65	7.50	10.30	18.00 max.	656L1542212T	25.00	19.30

Note : T = with thermal contact